



Statement of Materials, Construction

Revision: 1.1
Date: 4-Mar-05

LEAD-FREE -- 5L-SC70 -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element/Compound)	CAS Number	Material Mass (grams)	Material Weight % (of Total Pkg.)	Material Weight % (of Component)
1	Leadframe	Alloy 42	0.00256	Carbon (C)	7440-44-0	0.00000010	0.001940	0.004
				Iron (Fe)	7439-89-6	0.00150157	28.453877	58.655
				Manganese (Mn)	7439-96-5	0.00001101	0.208595	0.43
				Phosphorus(P)	7723-14-0	0.00000005	0.000970	0.002
				Cobalt (Co)	7440-48-4	0.00000077	0.014553	0.03
				Aluminium (Al)	7429-90-5	0.00000013	0.002426	0.005
				Silicon (Si)	7440-21-3	0.00000154	0.029106	0.06
				Sulphur (S)	7704-34-9	0.00000010	0.001940	0.004
				Nickel (Ni)	7440-02-0	0.00103859	19.680740	40.57
				Chromium (Cr)	7440-47-3	0.00000100	0.018919	0.039
				Cadmium (Cd)	7440-43-9	0.00000003	0.000485	0.001
			Silver (Ag)	7440-22-4	0.00000512	0.097021	0.2	
2	Die	Silicon Chip	0.00021	Silicon (Si)	7440-21-3	0.00021	3.95949	99.5
3	Die Attach Material	Conductive Epoxy	0.00002	Epoxy resin	Proprietary	0.0000030	0.05685	15
				Silver (Ag)	7440-22-4	0.00001600	0.30319	80
				Aromatic Amine	Proprietary	0.0000010	0.01895	5
4	Wire	Gold	0.00003	Gold (Au)	7440-57-5	0.00003	0.5684264	99.99
5	Lead Finish	Tin	0.0001872	Tin (Sn)	7440-31-5	0.00019	3.54734	100
6	Encapsulation	Epoxy Resin	0.00227	Fused Silica	60676-86-0	0.00166	31.53017	73.3
				Cristalline silica	14808-60-7	0.00009	1.72061	4
				Phenol resin	9003-35-4	0.00023	4.30152	10
				Solid epoxy resin	29690-82-2	0.0002270	4.30152	10
				Brominated epoxy	68928-70-1	0.0000045	0.08603	0.2
				Carbon black	1333-86-4	0.00002	0.43015	1
				Antimony trioxide	1309-64-4	0.00003	0.64523	1.5
Total Package weight			0.00528					

Note: Composition derived from MSDS and material C of C from Vendors;
Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead*	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%

* Lead is allowed up to 4% as an alloying agent in copper-based alloys